



LQFP-64 Lead Free RoHS Profile

Total Mass of the Unit specified (g):	Product / Component Description	Breakdown of product / component (e.g. chassis, transformer, lead frame, encapsulation, etc.)	Material Name (e.g. Sn alloy)	Substance Name (e.g. Copper (Cu))	CAS No.	Substance Mass (mg)	PPM	Additional Information
0.469	LQFP 64L	IC Chip	Silicon doped with aluminium	Silicon (Si)	7440-21-3	13	27,720	
		IC Chip	Silicon doped with aluminium	Aluminium (Al)	7429-90-5	0.019	41	
		IC Lead Frame	Copper alloy	Copper (Cu)	7440-50-8	215.1	458,656	C7025CDA7025
		IC Lead Frame	Copper alloy	Nickel (Ni)	7440-02-0	6.71	14,308	
		IC Lead Frame	Copper alloy	Silicon	7440-21-3	1.45	3,092	
		IC Lead Frame	Copper alloy	Magnesium	7439-95-4	0.34	725	
		IC Lead Frame	LF Plating	Silver (Ag)	7440-22-4	1.92	4,094	
		IC Sn solder plating	Tin solder	Tin (Sn)	7440-31-5	13.52	28,829	100% Matte Sn plating
		IC die attach	Epoxy filler - Ag	Silver (Ag)	7440-22-4	1.12	2,388	Ablestik 8340A
		IC die attach	Epoxy base material		N/A	0.4	853	
		IC bond wire	Gold wire	Gold (Au)	7440-57-5	2.3998	5,117	
		IC bond wire	Gold wire	Ion Impurities	N/A	0.0002	0	
		IC encapsulation	Molding compound	Multi-aromatic (resin)	N/A	26.18	55,823	Hitachi 9200THF
		IC encapsulation	Molding compound	Silica (SiO2)	60676-86-0	186.82	398,355	

Total mass (mg)	468.979
-----------------	---------